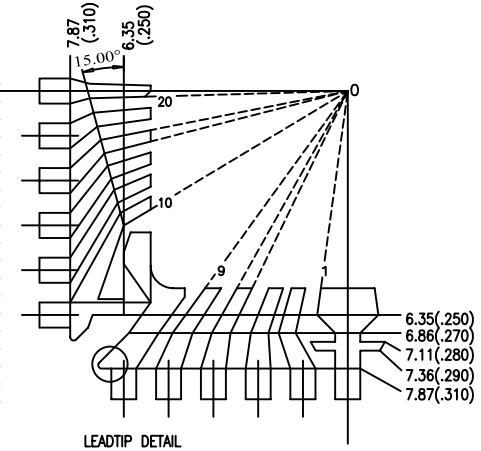
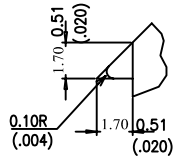
SSM P/N CQJ04409

NOTES
1. MATERIALS:
   CERAMIC TO OPAQUE.90–94% AL203
   SOLDER GLASS TO BE 7583.
   MAX PULLBACK TO BE 0.25(.010)
   FROM CERAMIC EDGE.
   DIE ATTACH AREA TO BE Au, 120
   MICROINCH MIN.
   LEAD FRAME TO BE ALLOY 42 OR
   EQUIVALENT WITH ALUMINIUM
   BOND PADS, 100 MICROINCH THICK
   AND 35 MILS IN LENGTH WITH NO
   PULL BACK.
3. THERE WILL BE NO UNSUPPORTED
   BOND PADS GRETER THEN 0.25(.010)
4. ADJACENT BOND PADS MUST BE
   CO–PLANAR WITHIN 0.15(.006).
   TOTAL CO–PLANARITY NO GREATER
   THAN 0.25(.010)
5. THERE WILL BE NO NICKS, CUTS
   OR GLASS IN THE BOND RADIUS.
6. MINIMUM INTERNAL METAL SEPARATION TO
   BE 0.20(.008)

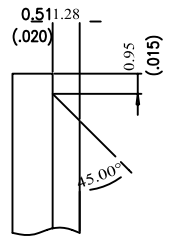
1	7.765
2	12.142
3	15.930
4	18.148
5	21.818
6	25.866
7	29.328
8	32.674
9	35.900
10	59.006
11	61.827
12	64.095
13	67.051
14	69.631
15	72.720
16	75.631
17	78.789
18	81.916
19	85.133
20	88.380



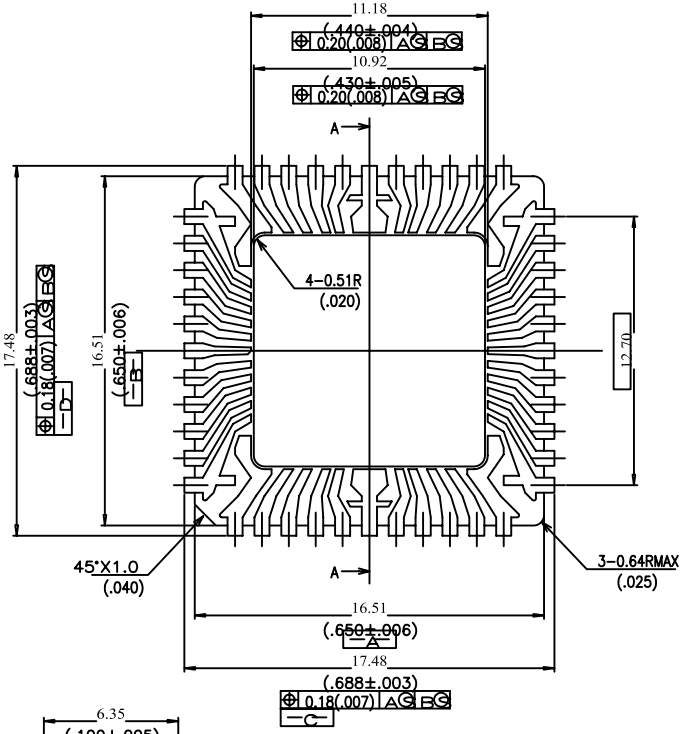
LEADTIP DETAIL

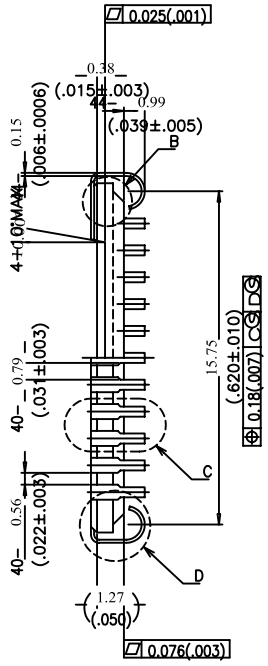


VIEW E

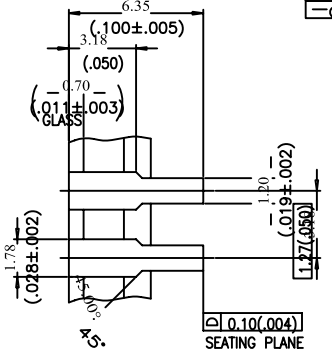


VIEW B

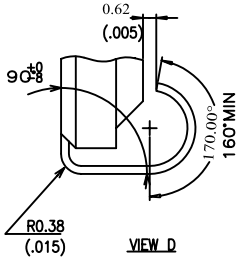




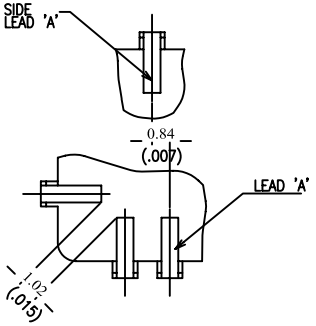
SECTION A–A



VIEW C



VIEW D



JEDEC TYPE

OPEN DRW.

CONTROLLED 7-30-03

MODIFICATIONS	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME 44LD QUAD CERPAC'J'(650–430)
SCALE (6 : 1) MATERIAL
TOLERANCES: UNLESS OTHERWISE SPECIFIED
DRAWN CHECKED APPROVED DATE JUL.20'88
KYOCERA CORPORATION KYOTO JAPAN
DWG No. QC–044253–J–1

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
www.spectrum-semi.com Phone: 408.435.5555 Fax: 408.435.8226